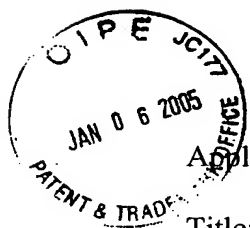


Shu

File Ref.: CITPAU05a



***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

Applicant: ATWATER, ET AL.

Title: WAFER BONDED VIRTUAL  
SUBSTRATE AND METHOD  
FOR FORMING THE SAME

Appl. No.: 10/761,918

Filing Date: 1/20/2004

Examiner: Unassigned

Art Unit: 1764

**PRELIMINARY AMENDMENT UNDER 37 CFR 1.115**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Prior to examination of the present Continuing Application, Applicant respectfully requests that the application be amended as follows:

**Amendments to the Specification** begin on page 2 of this document.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 10 of this document.

**Amendments to the Drawings** begin on page 15 of this document, and include an attached replacement drawing sheet and an annotated sheet showing changes.

**Remarks/Arguments** begin on page 16 of this document.

Please amend the application as follows: